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RENESAS

Application Note

USAGE OF μ PC1663, DC to VHF WIDEBAND DIFFERENTIAL INPUT AND OUTPUT AMPLIFIER IC

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1. GENERAL

The μ PC1663 is a differential input, differential output wideband amplifier IC that uses a high-frequency ($f_T = 6$ GHz) silicon bipolar process (called NESAT™ 1). This process improves bandwidth, phase characteristics, input noise voltage characteristics, and low power consumption compared to conventional HF-band differential amplifier ICs.

These features make this device suitable as a wideband amplifier in high-definition TVs, high-resolution monitors, broadcasting satellite receivers, and video cameras, as a sense amplifier in high-density CCD and optical pick-up products, or as a pulse amplifier for optical data links.

Note, however, that this device's wide frequency range means that extra caution is required with regard to factors such as oscillation.

This application note describes how to use the μ PC1663 and its application circuits.

2. BASIC OPERATIONS

2.1 Outline of Operations

Figure 1. Internal Equivalent Circuit

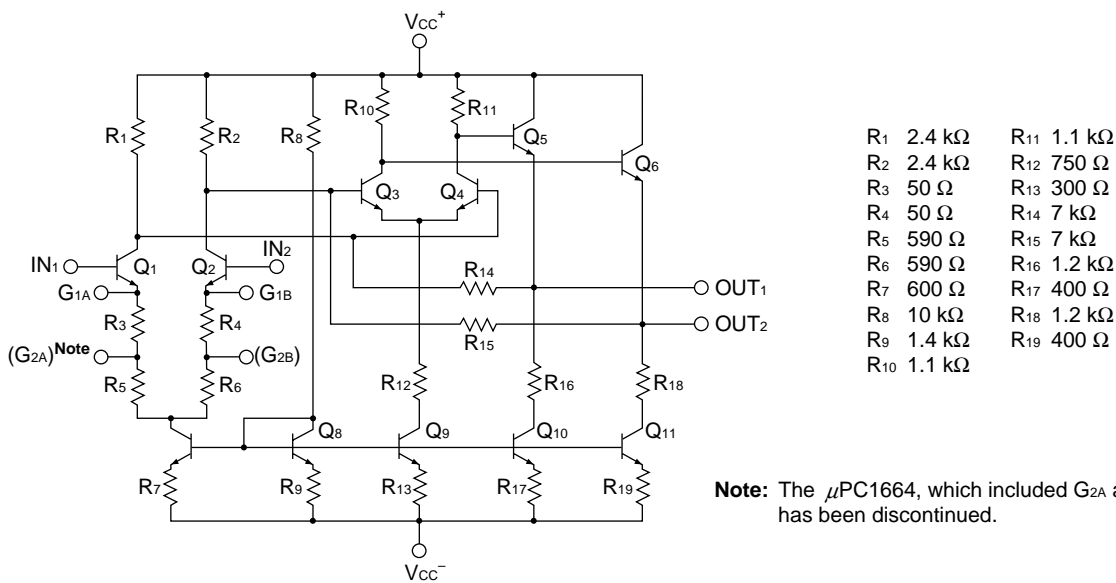


Figure 1 shows an internal equivalent circuit diagram of the μ PC1663. It is a DC direct-coupled amplifier in which two emitter-followers for transistors Q₅ and Q₆ are added to the two-stage differential configuration and in which feedback is propagated from the output via R₁₄ and R₁₅.

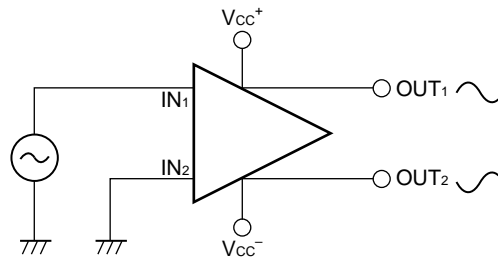
Since OUT₁ and OUT₂ are differential outputs, the output voltage changes to the reverse direction at precisely double the gain (single-end) of differential voltage ΔV_{DIF} added between the differential inputs IN₁ and IN₂. OUT₁ operates in phase with IN₁ and OUT₂ operates in phase with IN₂, so that, for example:

When IN₁ > IN₂, OUT₁ changes to positive and OUT₂ changes to negative

When IN₁ < IN₂, OUT₁ changes to negative and OUT₂ changes to positive

Accordingly, as is shown in Figure 2, if a sine wave is input to IN₁ when IN₂ is used as a ground, a sine wave having the same phase as the IN₁ input is output via OUT₁ and a sine wave having a 180° inverted phase is output via OUT₂.

Figure 2. Response to Sine Wave Input



Remark For purposes of simplification, the bypass capacitor and gain select pin have been omitted in some figures, such as Figure 2.

2.2 Determination of Gain

Given r_{e1} and r_{e2} as the resistance values corresponding to the input differential transistors Q_1 and Q_2 , the gain can be approximated via the following equations.

Gain A_{VD1} for IN_1 and OUT_1

$$A_{VD1} \doteq \frac{R_{14}}{r_{e1} + R_3 + R_5} \dots\dots\dots (1)$$

Gain A_{VD2} for IN_2 and OUT_2

$$A_{VD2} \doteq \frac{R_{15}}{r_{e2} + R_4 + R_6} \dots\dots\dots (2)$$

Consequently, assuming that $\Delta V_{DIF} = V_{IN1} - V_{IN2}$ as the differential voltage between IN_1 and IN_2 , the output voltage can be calculated as follows.

$$|\Delta OUT_1| = \frac{|\Delta V_{DIF}|}{2} \cdot A_{VD1} \dots\dots\dots (3)$$

$$|\Delta OUT_2| = \frac{|\Delta V_{DIF}|}{2} \cdot A_{VD2} \dots\dots\dots (4)$$

Since $A_{VD1} = A_{VD2}$, we can add equations (3) and (4) to obtain the following.

$$A_{VD1} = \frac{|\Delta OUT_1| + |\Delta OUT_2|}{|\Delta V_{DIF}|} \dots\dots\dots (5)$$

In equations (3), (4), and (5), A_{VD1} (A_{VD2}) represents the differential output gain corresponding to the differential input voltage. Therefore, the differential voltage gain and $A_{VD1}/2$ ($A_{VD2}/2$) are defined as single-end voltage gain since it represents only one-sided output corresponding to the differential input voltage.

2.3 Gain Adjustments

The gain values shown in equations (1) and (2) in section 2.2 above are determined according to the resistance applied to the emitter side of input differential transistors Q_1 and Q_2 .

Accordingly, in the equivalent circuit shown in Figure 1, a short between gain select pins G_{1A} and G_{1B} or insertion of an adjusting resistor can be used to adjust the gain in steps.

Setting a short between G_{1A} and G_{1B} sets maximum gain, with a typical value of 320 times the differential gain. Setting an open connection between G_{1A} and G_{1B} sets minimum gain, with a typical value of 10 times the differential gain. The electrical characteristics for the two gain select pin conditions, when Gain 1 is the maximum gain and Gain 2 is the minimum gain, are shown in Table 3.

If a gain adjusting resistor is inserted between G_{1A} and G_{1B} (as shown in Figure 4), any desired gain level can be obtained. Depending on the application circuit, if the R_s value is changed, the input voltage amplitude appears like it fluctuates due to changes in the interstage impedance, but the gain of the IC itself does not vary.

Figure 3. Pin Configuration of μ PC1663 (Top View)

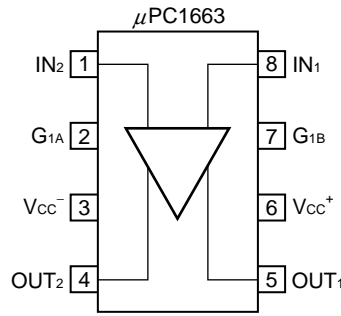
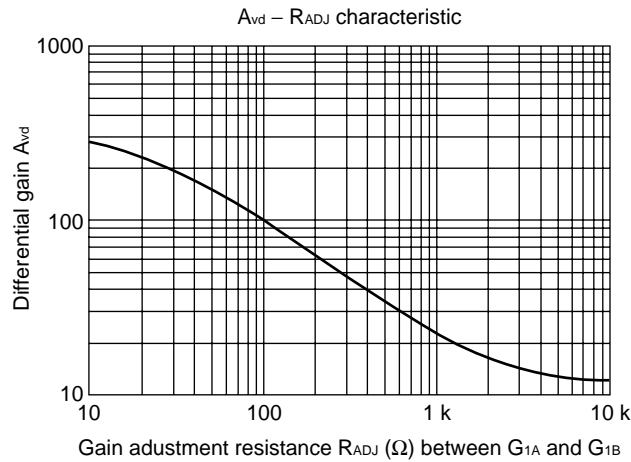


Figure 4. Differential Voltage Gain vs. Gain Adjustment Resistance Characteristics



3. ELECTRICAL CHARACTERISTICS

The absolute maximum ratings are listed in Table 1, recommended operating conditions in Table 2, and electrical characteristics in Table 3. Due to limitations that depend on the package, the supply voltage and temperature range differ slightly. The electrical characteristics are identical, however, because the same chip is employed.

Table 1. Absolute Maximum Ratings

Parameter	Symbol	Condition	μ PC1663C	μ PC1663G	μ PC1663GV	Unit
Power supply voltage	V_{CC}^{\pm}	$T_A = +25^{\circ}\text{C}$	± 8	± 7	± 7	V
Total dissipation	P_D	Note	500 ($T_A = +85^{\circ}\text{C}$)	280 ($T_A = +75^{\circ}\text{C}$)	280 ($T_A = +75^{\circ}\text{C}$)	mW
Differential input voltage	V_{ID}	$T_A = +25^{\circ}\text{C}$	± 5	± 5	± 5	V
Common mode input voltage	V_{ICM}	$T_A = +25^{\circ}\text{C}$, within V_{CC}^- to V_{CC}^+ range	± 6	± 6	± 6	V
Output current	I_O	$T_A = +25^{\circ}\text{C}$	35	35	35	mA
Operating ambient temperature	T_A		-45 to +85	-45 to +75	-45 to +75	$^{\circ}\text{C}$
Storage temperature	T_{stg}		-55 to +150	-55 to +150	-55 to +150	$^{\circ}\text{C}$

Note When mounted on a double sided copper clad $50 \times 50 \times 1.6$ mm epoxy glass PWB

Table 2. Recommended Operating Conditions

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Power supply voltage	V_{CC}^{\pm} (μ PC1663C)	± 2	± 6	± 7	V
Power supply voltage	V_{CC}^{\pm} (μ PC1663G, μ PC1663GV)	± 2	± 6	± 6.5	V
Output source current	$I_{O \text{ source}}$			20	mA
Output sink current	$I_{O \text{ sink}}$			2.5	mA
Operating frequency range	f_{opt}	DC		200	MHz

Table 3. Electrical Characteristics ($T_A = +25^{\circ}\text{C}$, $V_{CC}^{\pm} = \pm 6 \text{ V}$)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit	
Differential voltage gain	Gain 1	A_{vd}	$f = 10 \text{ MHz}$ ^(Note 1)	200	320	500	—
	Gain 2		$f = 10 \text{ MHz}$ ^(Note 2)	8	10	12	
Bandwidth	Gain 1	BW	$R_S = 50 \Omega$ (3 dB down point)	—	120	—	MHz
	Gain 2			—	700	—	
Rise time	Gain 1	t_r	$R_S = 50 \Omega$, $V_{out} = 1 \text{ V}_{P-P}$	—	2.9	—	ns
	Gain 2			—	2.7	—	
Propagation delay	Gain 1	t_{pd}	$R_S = 50 \Omega$, $V_{out} = 1 \text{ V}_{P-P}$	—	2	—	ns
	Gain 2			—	1.2	—	
Input resistance	Gain 1	R_{in}		—	4.0	—	k Ω
	Gain 2			50	180	—	
Input capacitance	C_{in}		—	2	—	pF	
Input offset current	I_{IO}		—	0.4	5.0	μA	
Input bias current	I_R		—	20	40	μA	
Input noise voltage	V_n	$R_S = 50 \Omega$, 10 k to 10 MHz	—	3	—	$\mu\text{V}_{r.m.s}$	
Input voltage range	V_i		± 1.0	—	—	V	
Common mode rejection ratio	Gain 2	CMR	$V_{cm} = \pm 1 \text{ V}$, $f \leq 100 \text{ kHz}$	53	94	—	dB
Supply voltage rejection ratio	SVR	$\Delta V = \pm 0.5 \text{ V}$	50	70	—	dB	
Output offset voltage	Gain 1	$V_{O(off)}$	$V_{O(off)} = OUT_1 - OUT_2 $	—	0.3	1.5	V
	Gain 2			—	0.1	1.0	
Output common mode voltage	$V_{O(CM)}$		2.4	2.9	3.4	V	
Output voltage swing	V_{OP-P}	Single end	3.0	4.0	—	V_{P-P}	
Output sink current	I_{sink}		2.5	3.6	—	mA	
Power supply current	I_{CC}		—	13	20	mA	

Notes 1. Gain 1 is when gain select pins G_{1A} and G_{1B} are connected

2. Gain 2 is when none of the gain select pins are connected

Remark The detailed specifications and package drawings should be referred to the data sheet (G11024E).

The electrical characteristics are defined as follows.

3.1 Differential Voltage Gain (A_{VD})

As was described in section 2.2, this indicates the ratio between the differential input and differential output voltage.

$$A_{VD} = \frac{|\Delta OUT_1| + |\Delta OUT_2|}{|\Delta V_{DIF}|} \quad \text{or} \quad \frac{\Delta |OUT_1 - \Delta OUT_2|}{|\Delta V_{DIF}|}$$

The single-end gain (A_{VS}) for single-side output is expressed as one half of A_{VD} shown below.

$$A_{VS} = \frac{|\Delta OUT_1|}{|\Delta V_{DIF}|} \quad \text{or} \quad \frac{|\Delta OUT_2|}{|\Delta V_{DIF}|}$$

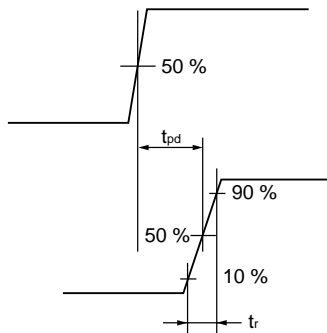
3.2 Bandwidth (BW)

This is defined as the bandwidth when there is a 3-dB down gain ($1 / \sqrt{2}$) in relation to the DC gain.

3.3 Rise Time (t_r) and Propagation Delay Time (t_{pd})

These are defined as shown below for this IC.

Figure 5. Measurement Conditions for t_{pd} and t_r



3.4 Input Resistance (R_{in})

This indicates the ratio of the change in the input bias voltage (ΔI_B) to the change in the input voltage (ΔV_{IN}).

$$R_{IN} = \Delta V_{IN} / \Delta I_B$$

The input resistance is defined as the product of the input transistor's current gain β and the emitter resistance. Therefore, this value is reduced in relation to higher gain values.

3.5 Input Capacitance (C_{in})

This indicates the capacitance between the input and the GND.

3.6 Input Offset Current (I_{io})

This is the offset current of the dual input bias current.

$$I_{io} = |I_{B1} - I_{B2}|$$

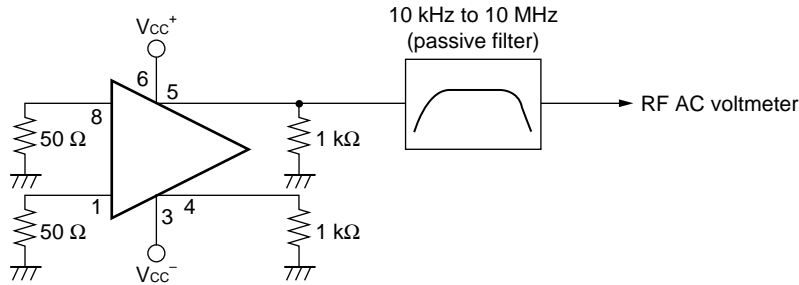
3.7 Input Bias Current (I_b)

This indicates the base current at input transistors Q₁ and Q₂.

3.8 Input Noise Voltage (V_n)

In Figure 6, the value measured by an RF AC voltmeter is divided by the single-end gain value.

Figure 6. Input Noise Voltage Measurement Circuit

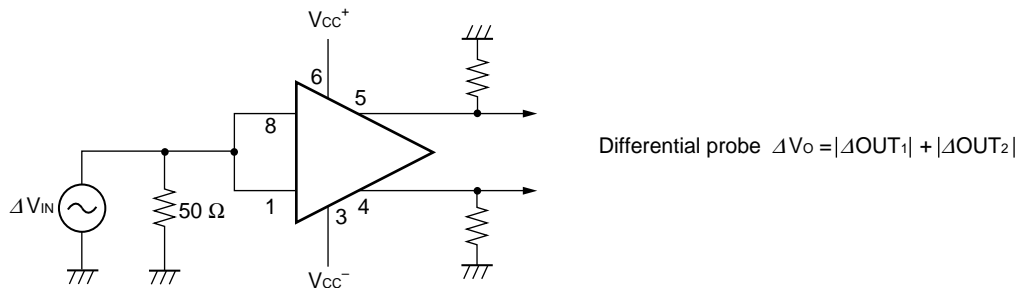


3.9 Input Voltage Range (V_i)

This indicates the input voltage range for normal operation, during which input signals must be within this range. With the intermediate potential between V_{cc}⁺ and V_{cc}⁻ as the center, the input voltage range is guaranteed within ±1 V (when V_{cc}⁺ – V_{cc}⁻ = 12 V).

3.10 Common Mode Rejection Ratio (CMR)

Figure 7. Common Mode Rejection Ratio Measurement Circuit



This indicates the rate of variation in the input conversion offset relative to the common mode input signal. This can be expressed as follows, based on the circuit shown in Figure 7.

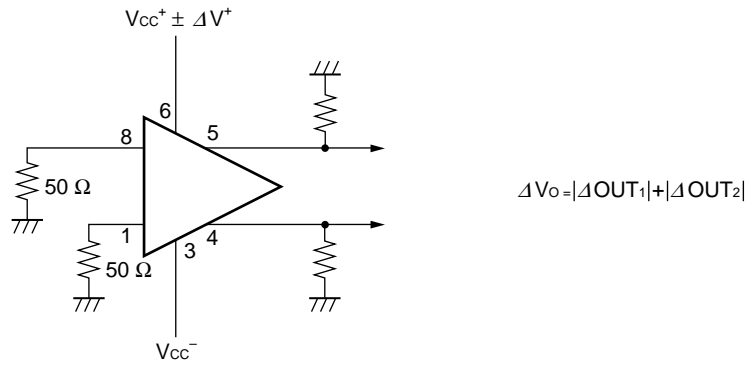
$$CMR = 20 \log \frac{\Delta V_{IN}}{\Delta V_o} \cdot A_{VD}$$

3.11 Supply Voltage Rejection Ratio (SVR)

This indicates the rate of variation in the input conversion offset relative to the supply voltage. This can be expressed as follows, based on the circuit shown in Figure 8.

$$SVR = 20 \log \frac{\Delta V^+}{\Delta V_o} \cdot A_{VD}$$

Figure 8. Supply Voltage Rejection Ratio Measurement Circuit (V⁺ side)



3.12 Output Offset Voltage ($V_{O(off)}$)

This indicates the DC voltage difference between both outputs when both of the differential inputs voltage is not applied.

$$V_{O(off)} = |OUT_1 - OUT_2|$$

3.13 Output Common Mode Voltage ($V_{O(CM)}$)

This indicates the average value from both output's DC voltages when both of the differential inputs voltage is not applied.

$$V_{O(CM)} = \frac{OUT_1 + OUT_2}{2}$$

3.14 Output Voltage Swing ($V_{O(p-p)}$)

This indicates the maximum amplitude (swing) that occurs without distortion, mainly in the output common mode voltage.

3.15 Output Sink Current

This indicates the sink current capacity of transistors Q₁₀ and Q₁₁. If a current that exceeds this value is accepted, the output voltage swing is greatly reduced.

3.16 Power Supply Current

This indicates the circuit current and does not include the output load current.

4. PRECAUTIONS FOR DESIGN IN

4.1 Cautions on Layout and Wiring

In high-frequency circuits, the PCB design can considerably influence circuit performance.

When using this device with an especially high gain, you must note that oscillation might occur even when there is only a slight amount of external feedback.

The following cautions concern the device mounting layout.

- Form as wide an area as possible for the ground pattern so as to prevent feedback due to conductor inductance (a double sided copper clad epoxy glass PWB is recommended).
- Make the leads from external components and the link wiring between front and rear components as short as possible.
- Use a single ground as the ground for input/output circuit and the power supply.
- Form the ground pattern to shield the input and output wiring so as to prevent feedback due to stray capacitance.
- Lay out the output signal current path at a distance from the input wiring.
- The power supply is bypassed very near to the IC's power supply pin by a small-inductance, high-frequency capacitor. If the power supply wiring is long, insert a small resistance (up to 10 Ω) in series.
- The ground for the bypass capacitor should be laid out in order to form a loop only with the power supply line so as to prevent the high-frequency current that runs throughout the PCB from entering the input.

4.2 Cautions on External Circuit

This IC features greatly improved phase characteristics, such that the characteristics inherent to this IC make it one of the more stable wideband amplifier ICs. However, the following cautions should be noted when this IC is used in application circuits.

- Whenever possible, the signal source resistance values should be the same for the two inputs. Signal source resistance values should be minimized, with 1 k Ω maximum (If the signal source impedance is too large, the input amplitude becomes large and the output will become saturated).
- Whenever possible, the load resistance values should be the same for the two outputs.

* For this IC, it is essential that a balance be maintained between the two lines (IN₁ to OUT₁ and IN₂ to OUT₂) in the application circuit.

4.3 Other Caution Points

- Use of single (power) supply

This IC can be used with a single supply if the input voltage is biased at the intermediate between V_{CC}^+ and V_{CC}^- , as is shown in the application circuit example in the data sheet. More detailed circuit examples and their characteristics are shown in Figure 9 and Tables 4 and 5.

Note, however, that in this case the load current along R_L is more than twice as great as when the load is connected with \pm power supply to a ground (recommended: max. 20 mA, $I_o = \frac{V_{O(CM)}}{R_L}$).

Figure 9. Example Using Single Power Supply

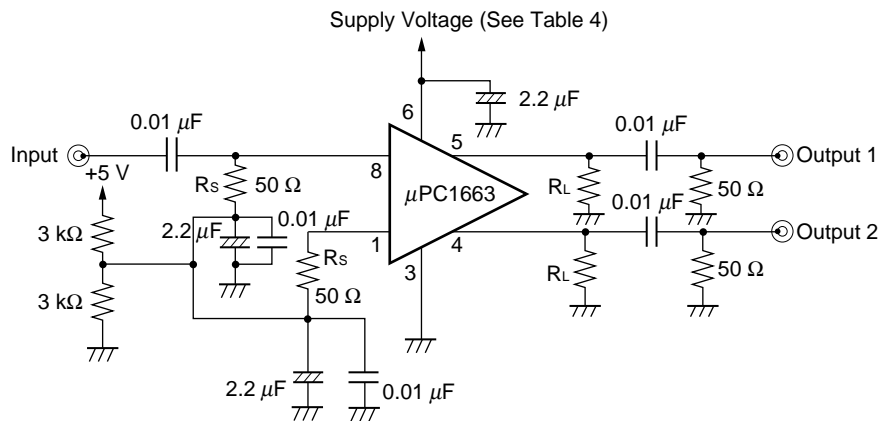


Table 4. Reference Usage Range

Parameter	Symbol	Condition	μPC1663C	μPC1663G	μPC1663GV	Unit
Supply voltage	$V_{CC^+} - V_{CC^-}$	Single power supply	-0.3 to +16	-0.3 to +14	-0.3 to +14	V

Table 5. +5 V Single Power Supply Operation Performance (Based on Figure 9)

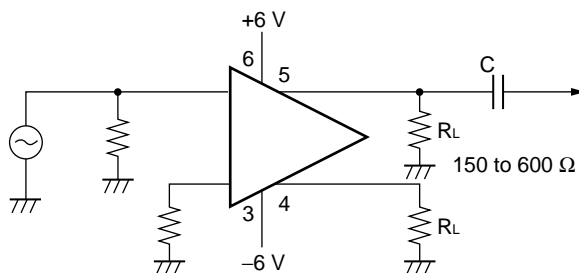
Parameter		Condition	Characteristics	Unit
Gain	Gain 1	15 MHz	35	dB
	Gain 2		11	
Bandwidth	Gain 1	3 dB down point	106	MHz
	Gain 2		115	
Rise time	Gain 1	$R_S = 50 \Omega, V_{OUT} = 80 \text{ mV}_{P-P}$	2.2	ns
Propagation delay time	Gain 1	$R_S = 50 \Omega, V_{OUT} = 80 \text{ mV}_{P-P}$	2.8	ns
	Gain 2	$R_S = 50 \Omega, V_{OUT} = 60 \text{ mV}_{P-P}$	1.8	
Phase	Gain 1	100 MHz	-123	degree
	Gain 2		-93	
Output, Max.	$R_L = 240 \Omega$	$R_L = 50 \Omega$	5.0	dBm
	$R_L = 910 \Omega$	15 MHz	0	
	$R_L = 80 \Omega$		-11.5	

- Driving a low-impedance line

As was described in section 3.15 above, the sink current of the IC itself is only 3.6 mA (TYP.), which is inadequate for driving a low-impedance line such as a video line. As is shown in Figure 10, it is possible to drive a low-impedance line if a bypass resistor rated between 150 and 600 Ω is connected and a capacitor coupling is used to link the increased drive capacity of the output-level emitter-follower.

In this case, the output current ($I_o = (V_{O(CM)} / R_L)$) generated based on the R_L value should not be more than 20 mA.

Figure 10. Driving a Low Impedance Line



5. APPLICATION CIRCUIT EXAMPLES

5.1 Video Line Driver Circuit Example

Figure 11. Video Line Driver Circuit Example

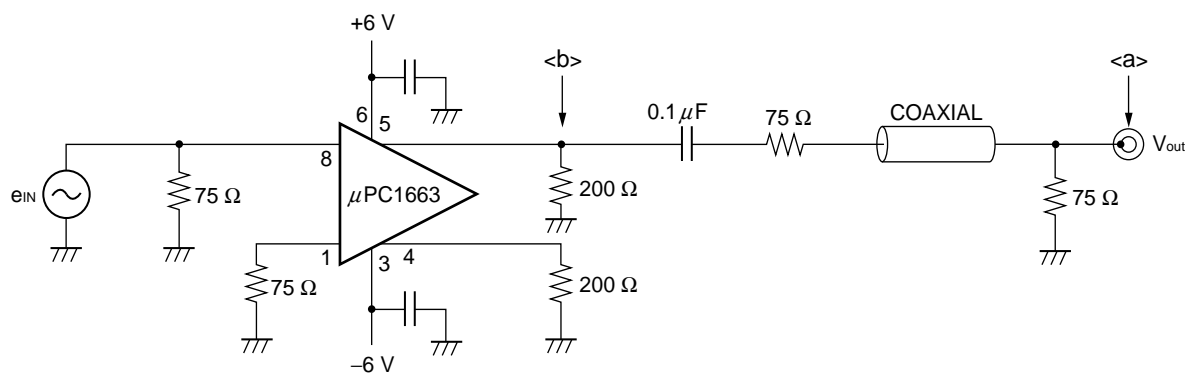
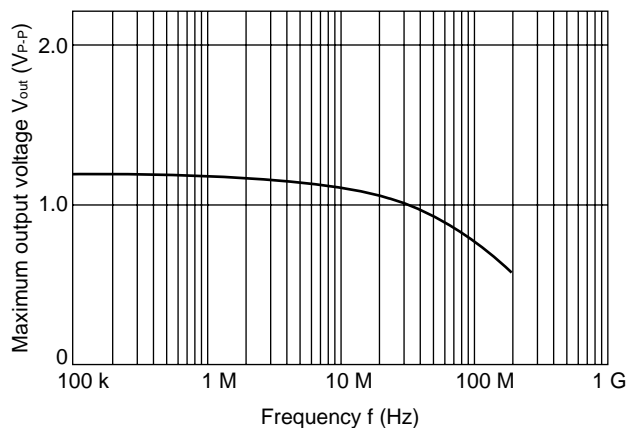
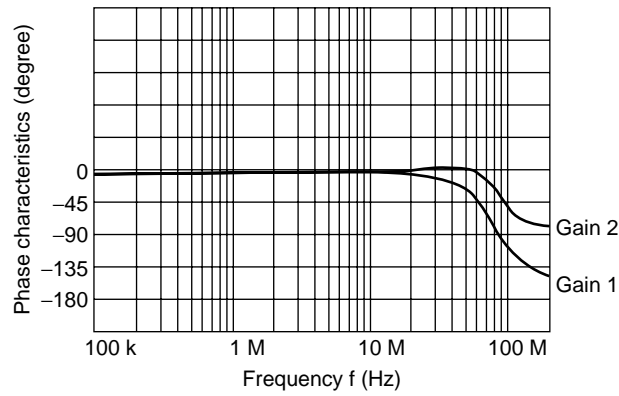


Figure 12. V_{out} vs. f Characteristics (Video Line, Single End)



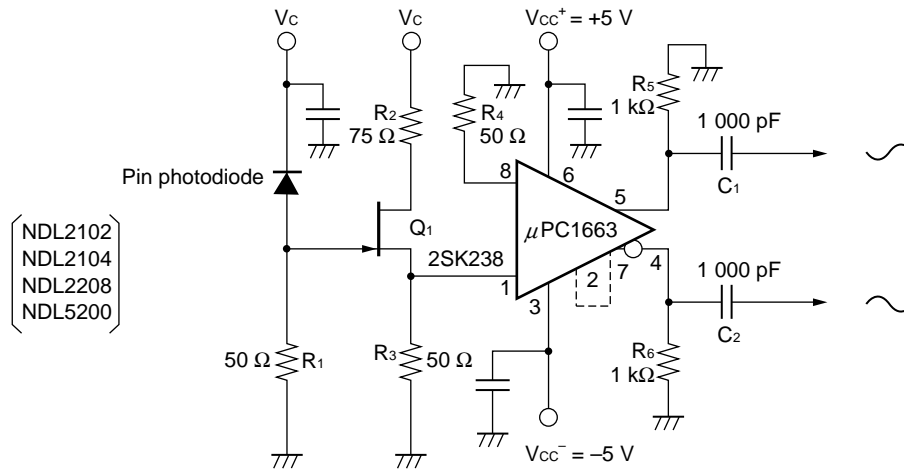
Remark The measurement results in Figure 12 are the values of point <a> in Figure 11 of the application circuit. The values for the μ PC1663 are those of point , therefore when converted, they are equivalent to approximately twice the value of V_{out} at point <a>. Because the measured values at point <a> are single-end, in the case of differential I/O, the values of points <a> and are twice the value of the single-end values.

Figure 13. Phase Characteristics vs. Frequency Characteristics



5.2 Optical Signal Detection Circuit Example

Figure 14. Optical Signal Detection Circuit Example



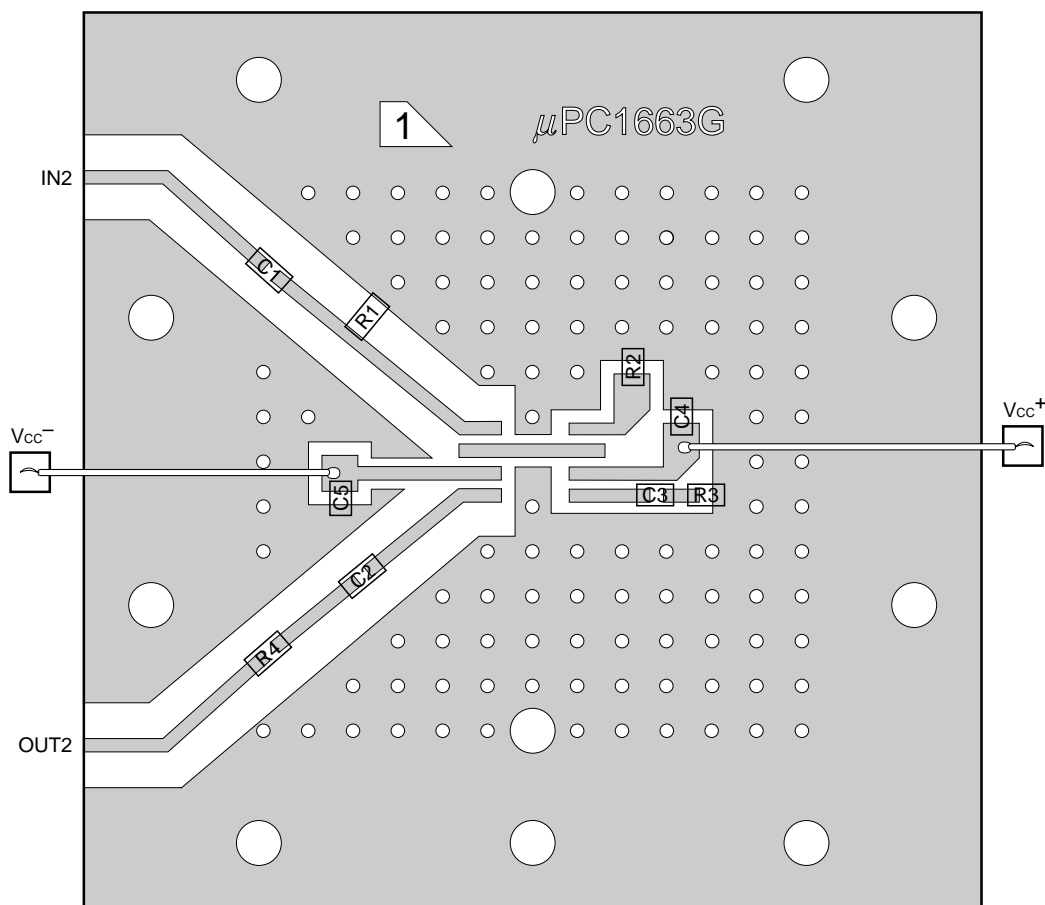
Since a high gain value may lower the IC's input impedance, stable operation can be ensured by including an FET buffer (source follower), as is shown in Figure 14. This FET buffer also shifts the level of the input voltage from the diode. For detail on the FET and PIN photodiode, see the data sheet for each product.

6. EXAMPLE OF MOUNTING MEASURING CIRCUIT ON PRINTED BOARD

6.1 Example of Mounting μ PC1663G on Printed Board

Figure 15 shows an example of mounting of 8-pin SOP 225-mil type product on a PCB for use in the test circuit described in the μ PC1663 data sheet. The evaluation board in Figure 15 is designed for single-end test circuit of IN2 input and OUT2 output.

Figure 15. Example of assembled test Circuit on Evaluation Board



Parts Table

No.	Value
C1 to 3	0.1 μ F
C4 to 5	1000 pF
R1 to 2	50 Ω
R3	1 k Ω
R4	950 Ω *

Notes on Printed Board

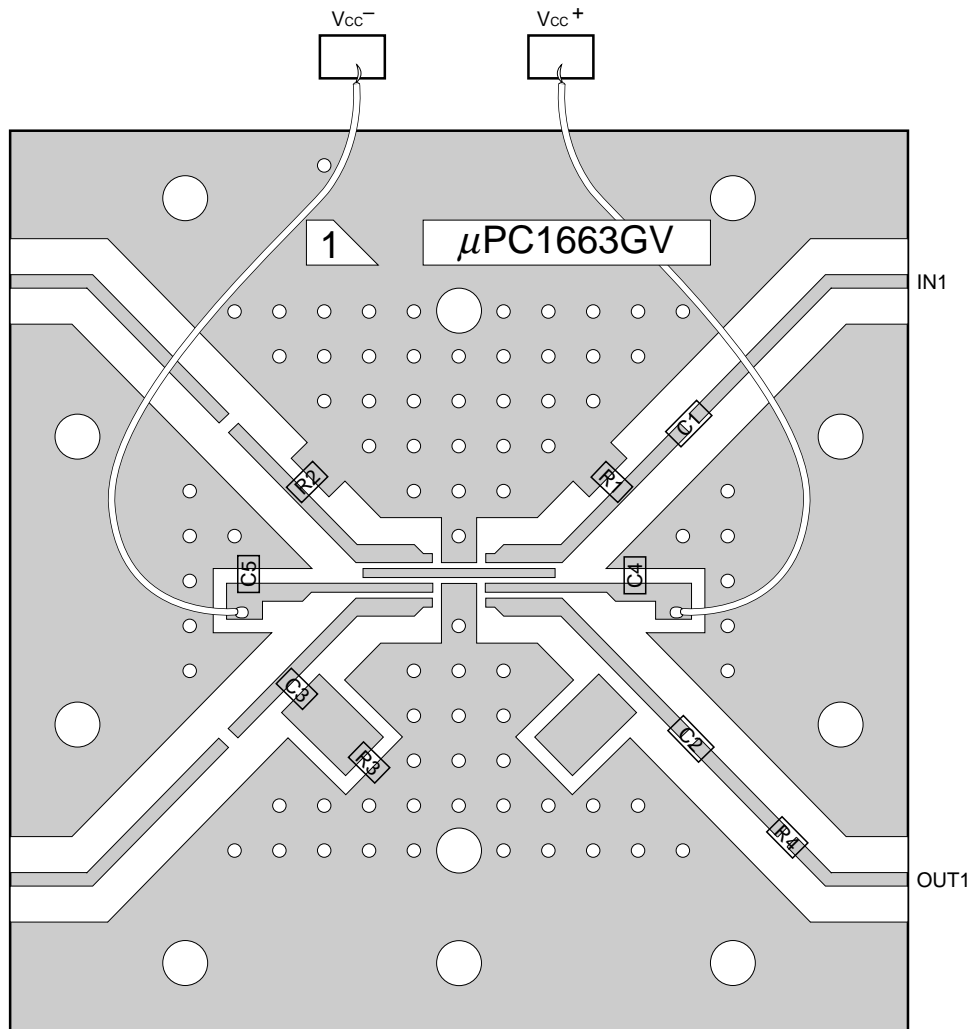
- (*1) 35- μ m copper patterning on both sides of 50 \times 50 \times 0.4-mm polyimide board
- (*2) Rear side ground pattern
- (*3) Solder plating of patterning side
- (*4) \circ \bigcirc is through-hole.
- (*5) To mount C2, pattern should be cut.

* R4 is the value obtained by subtracting the impedance of the measuring instrument from R3.

6.2 Example of Mounting μ PC1663GV on Printed Board

Figure 16 shows an example of mounting of 8-pin SSOP 175-mil type product on a PCB for use in the test circuit described in the μ PC1663 data sheet. This evaluation board can be used either for a single-end or differential amplifier. The assembled example in Figure 16 is for a single-end amplifier and provides one IN1 and one OUT1 pins.

Figure 16. Example of assembled test Circuit on Evaluation Board



Parts Table

No.	Value
C1 to 3	0.1 μ F
C4 to 5	1000 pF
R1 to 2	50 Ω
R3	1 k Ω
R4	950 Ω *

Notes on Printed Board

- (*1) 35- μ m copper patterning on both sides of 50 \times 50 \times 0.4-mm polyimide board
- (*2) Rear side ground pattern
- (*3) Solder plating of patterning side
- (*4) \circ \bigcirc is through-hole.
- (*5) To mount R4, pattern should be cut.

* R4 is the value obtained by subtracting the impedance of the measuring instrument from R3.

7. CONCLUSION

The usage of the μ PC1663 DC to VHF wideband differential input and output amplifier IC has been described above.

Another product that uses a high-frequency process, the μ PC2726T, is also offered as an L-band differential input and differential output wideband amplifier IC that operates up to 1.6 GHz.

Reference Materials

μ PC1663 Data Sheet (Document No. G11024E)

μ PC2726T Data Sheet (Document No. P10873E)

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